

MAIL STOP ISSUE FEE

Notice of Allowance: September 20, 2004

PATENT

Docket No. MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**RECEIVED
CENTRAL FAX CENTER**

Applicant : Lee, Teck Kheng
 Serial No. : 10/050,507
 Filing Date : January 16, 2002
 For: Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
 Group Art Unit: 2813
 Confirmation No.: 7687
 Examiner : THOMPSON, Craig

SEP 27 2004

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10
 I hereby certify that, on the date shown below, this correspondence is being transmitted by facsimile to Fax No.
 (703) 872-9306 addressed to Examiner Craig Thompson at the U.S. Patent and Trademark Office.

Date: 9-27-04*Patricia Rickure*

Mail Stop ISSUE FEE
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

COMMUNICATION

Sir:

Enclosed herewith is a copy of the following documents that were earlier submitted to the Examiner:

- Information Disclosure Statement/Form 1449 submitted by first class mail on September 9, 2004 with PTO-stamped return postcard.
- Information Disclosure Statement/Form 1449 submitted by facsimile on September 20, 2004 with Auto-Reply Facsimile Transmission. The PAIR records indicate that this IDS/Form 1449 was entered for this application.

The Examiner is requested to acknowledge receipt of the above documents, and return an initialed copy of each of the Forms 1449 to Applicant.

Respectfully submitted,

Kristine M. Strodthoff
 Kristine M. Strodthoff
 Reg. No. 34,259

Dated: September 27, 2004

WHYTE HIRSCHBOECK DUDEK S.C.
 555 East Wells Street, Suite 1900
 Milwaukee, Wisconsin 53202-3819
 (414) 273-2100
 Customer No. 31870

BEST AVAILABLE COPY

MKE/973752.1

THE STAMP OF THE U.S. PATENT OFFICE HEREON DENOTES RECEIPT
ON THE DATE STAMPED OF:

In re Application of : Lee, Teck Kheng
Serial No. : 10/050,507
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Poly Chip on
Flex for Die Stacking
Atty. Docket No. : MTI-31607

IIDS Transmittal

Enclosures: IIDS Transmittal; PTO-1449; twenty-two (22) references and return
postcard.

DATE MAILED: September 9, 2004
FIRST CLASS MAIL



KJS

USPTO 9/20/2004 10:33 AM PAGE 1/001 Fax Server
 :Auto-reply fax to 414 224 5834 COMPANY:

Auto-Reply Facsimile Transmission



TO:

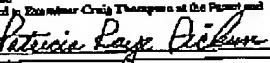
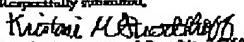
Fax Sender at 414 224 5834

Fax Information
 Date Received:
 Total Pages:

9/20/2004 10:30:43 AM [Eastern Daylight Time]
 5 (including cover page)

ADVISORY: This is an automatically generated return receipt confirmation of the facsimile transmission received by the Office. Please check to make sure that the number of pages listed as received in Total Pages above matches what was intended to be sent. Applicants are advised to retain this receipt in the unlikely event that proof of this facsimile transmission is necessary. Applicants are also advised to use the certificate of facsimile transmission procedures set forth in 37 CFR 1.8(a) and (b), 37 CFR 1.6(f). Trademark Applicants, also see the Trademark Manual of Examining Procedure (TMEP) section 306 et seq.

Received
 Cover
 Page

09/20/04 09:38 FAX 414 224 5834 W. H. D.		006
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE		
Patent	Attorney Docket No.: MII-31607	
In re Application of	Teak Kheng Lee	
Serial No.	10/050,507	
Confirmation No.	7687	
Filing Date	January 16, 2002	
For	Elimination of RDL Using Tape Base Flip Chip on Flex for Dic Stacking	
Group Art Unit	2312	
CERTIFICATION UNDER 37 CFR 1.14(a) and 1.14		
I hereby certify that, on the date shown below, this communication is being:		
Deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231		
<input type="checkbox"/> 37 CFR 1.14(a) <input checked="" type="checkbox"/> 37 CFR 1.14 with sufficient postage on first class mail <input checked="" type="checkbox"/> As "Official Mail from Office to Addressee" Mailing L40477VA.		
<input checked="" type="checkbox"/> transmitted by facsimile to File No. 091-672-5006 addressed to Examiner Craig Thompson at the Patent and Trademark Office.		
Date	9-20-04 2004	
 Kristine M. Schommer, Reg. No. 34259		
Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450		
INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(b)		
Sir:	In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. § 1.56, listed on the attached Form PTO-1449 are those patent and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.	
Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that these references be made of record in the present application, and that an initialled copy of the attached Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.		
Respectfully submitted,		
 Kristine M. Schommer, Reg. No. 34259		
Date:	September 20, 2004	
WHYTE HIRSCHBOCK DUDYK, S.C. 555 East Wells Street, Suite 1900 Milwaukee, Wisconsin 53202-3819 (414) 273-2100 Customer No. 31870		

1 of 1
 PAGE 15 * RCVD AT 9/20/2004 10:30:43 AM [Eastern Daylight Time] * SVR:USPTO-EFXRF-1/9 * DNIS:8729306 * CSID:414 224 5834 * DURATION (mm:ss):04:00:01 * 001

RECEIVED
CENTRAL FAX CENTER

SEP 27 2004

Patent

Attorney Docket No.: MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
 Serial No. : 10/050,507
 Confirmation No. : 7687
 Filing Date : January 16, 2002
 For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
 Group Art Unit : 2812

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

Mailing

- deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231
- 37 CFR 1.8(a)
- with sufficient postage as first class mail
- As "Express Mail Post Office to Addressee" Mailing Label No. _____
- Transmission
- transmitted by facsimile to Fax No.: addressed to Examiner at the Patent and Trademark Office.

Date: _____, 2004

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached Form PTO-1449 are those patents and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that these references be made of record in the present application, and that an initialed copy of the attached Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.

Respectfully submitted,

Kristine M. Strothoff, Reg. No. 34259

Dated: September 9, 2004

WHYTE HIRSCHBOECK DUDEK S.C.
 555 East Wells Street, Suite 1900
 Milwaukee, Wisconsin 53202-3819
 (414) 273-2100
 Customer No.: 31870

DOCKET BY B5 9/21/04

CDC BY _____

ATP INITIALS _____

MKE/748404.1

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313		ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		Applicant Teck Kheng Lee	Confirmation No. 7687
		Filing Date January 16, 2002	Group Art Unit 2813

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initial		Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
	A1	2000-183082	06-30-00	JP	H01L	21/566	Abstract
	A2	2001077294	03-23-01	JP	H01L	25/065	Yes
	A3	99/65282	12-16-99	WO	H05K	1/11	N/A

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initial	Non-Patent Document
B1	Copy of Australian Patent Office, Search Report, 30 May 2003, 4 pages.
B2	Al-sarawi, S. et al., "A Review of 3-D Packaging Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol 21, Issue 1, Feb. 1998, pp. 2-14.
B3	Andros, F. et al., "TBGA Package Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol. 17, Issue 4, Nov. 1994, pp. 564-568.
B4	Clot, Ph. et al., "Flip-Chip on Flex for 3D Packaging," 1999. 24 th IEEE/CPMT, 18-19 Oct. 1999, pp. 36-41.
B5	Ferrando, F. et al., "Industrial Approach of a Flip-Chip Method Using the Stud-Bumps With a Non-Conductive Paste," <i>Adhesive Joining and Coating Technology in Electronics Manufacturing</i> , 2000. Proceedings. 4 th International Conference on, 18-21, June 2000, pp. 205-211.
B6	Gallagher, C. et al., "A Fully Additive, Polymeric Process for the Fabrication and Assembly of Substrate and Component Level Packaging," <i>The First IEEE International Symposium on Polymeric Electronics Packaging</i> , 26-30, Oct. 1997, pp. 56-63.
B7	Geissinger, J. et al., "Tape Based CSP Package Supports Fine Pitch Wirebonding," <i>Electronics Manufacturing Technology Symposium</i> , 2002, IEMT 2002, 27 th Annual IEEE/SEMI International, 17-18 July 2002, pp. 41-452.
B8	Hatanaka, H., "Packaging Processes Using Flip Chip Bonder and Future Directions of Technology Development," <i>Electronics Packaging Technology Conference</i> , 2002. 4 th , 10-12, Dec. 2002, pp. 434-439.
B9	Haug, R. et al., "Low-Cost Direct Chip Attach: Comparison of SMD Compatible FC Soldering with Anisotropically Conductive Adhesive FC Bonding," <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , Vol. 23, No. 1, Jan 2000, pp. 12-18.

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

MKE/968557.1

1 of 2

09-09-2004

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. <hr/> MTI-31607 <hr/> Applicant <hr/> Teck Kheng Lee <hr/> Filing Date <hr/> January 16, 2002	Serial No. <hr/> 10/050,507 <hr/> Confirmation No. <hr/> 7687 <hr/> Group Art Unit <hr/> 2813
---	---	--

Examiner Initial	Non-Patent Document
B10	Isaak, H. et al., "Development of Flex Stackable Carriers" IEEE Electronic Components and Technology Conference, 2000 Proceedings 50th, 5/21/2000-5/24/2000, Las Vegas, NV, USA, pp. 378-84, IEEE Catalog No: 00CH37070.
B11	Kloeser, J. et al., "Fine Pitch Stencil Printing of Sn/Pb and Lead Free Solders for Flip Chip Technology," <i>IEEE Transactions of CPMT - Part C</i> , vol 21, No. 1, 1998, pp. 41-49.
B12	Kheng et al., "Enhancement of Moisture Sensitivity Performance of a FBGA," <i>Proceedings of International Symposium on Electronic Materials & Packaging</i> , 2000, pp. 470-475.
B13	Li, L. et al., "Stencil Printing Process Development for Flip Chip Interconnect," <i>IEEE Transactions Part C: Electronics Packaging Manufacturing</i> , Vol. 23, Issue 3, July 2000, pp. 165-170.
B14	Lyons, A. et al., "A New Approach to Using Anisotropically Conductive Adhesives for Flip-Chip Assembly, Part A," <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 19, Issue 1, March 1996, pp. 5-11.
B15	Teo, Y. et al., "Enhancing Moisture Resistance of PBGA," <i>Electronic Components and Technology Conference</i> , 1998, 48 th IEEE, 25-28 May 1998, pp. 930-935.
B16	Tutsch, T. et al., "Wafer Level CSP using Low Cost Electroless Redistribution Layer," <i>Electronic Components and Technology Conference</i> , 2000, 2000 Proceedings. 50 th , 21-24 May 2000, pp. Pages: 107-113.
B17	"The 2003 International Technology Roadmap for Semiconductors: Assembly and Packaging", pp. 1-22
B18	Tsui, C. et al. "Pad Distribution Technology for Flip Chip Applications", <i>1998 Electronic Components and Technology Conference</i> , pp. 1098-1102
B19	Xiao, G. et al., "Reliability Study and Failure Analysis of Fine Pitch Solder-Bumped Flip Chip on Low-Cost Flexible Substrate Without Using Stiffener," IEEE, 2002. Proceedings 52 nd , 28-31 May 2002, pp. 112-118.

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

RECEIVED
CENTRAL FAX CENTER

SEP 27 2004

Patent

Attorney Docket No.: MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Teck Kheng Lee
 Serial No. : 10/050,507
 Confirmation No. : 7687
 Filing Date : January 16, 2002
 For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die
 Stacking
 Group Art Unit : 2812

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being:

Mailing

deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

37 CFR 1.10

with sufficient postage as first class mail
 Mailing Label No.

As "Express Mail Post Office to Addressee"

transmitted by facsimile to Fax No.: 703-872-9306 addressed to Examiner Craig Thompson at the Patent and Trademark Office.

Transmission

Date: 4-20-04, 2004

Patricia Page Pickens

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97/98

Sir:

In compliance with Applicant's duty of disclosure as set forth in 37 C.F.R. §1.56, listed on the attached Form PTO-1449 are those patents and other publications known to Applicant which may be considered material to the patentability of the claims of the above-identified application.

Applicant respectfully requests that the Examiner consider the documents listed on the attached Form PTO-1449, that these references be made of record in the present application, and that an initialed copy of the attached Form PTO-1449 be returned to the undersigned in accordance with MPEP 609.

Respectfully submitted,

Kristine M. Strodthoff
 Kristine M. Strodthoff, Reg. No. 34259

Dated: September 20, 2004

WHYTE HIRSCHBOECK DUDEK S.C.
 555 East Wells Street, Suite 1900
 Milwaukee, Wisconsin 53202-3819
 (414) 273-2100
 Customer No.: 31870

DOCKET BY BS 9/21/04

CDC BY _____

MKE/748404.1

ATTY INITIALS _____ 1 of 1

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313	ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant Teck Kheng Lee	Confirmation No. 7687
	Filing Date January 16, 2002	Group Art Unit 2813

U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub-Class
A1	3,239,496	03/1966	Jursich		
A2	4,074,342	02/1978	Honn et al.		
A3	4,807,021	02/1989	Okumura		
A4	4,818,728	04/1989	Rai et al.		
A5	5,366,794	11/1994	Nakao		
A6	5,385,869	01/1995	Liu et al.		
A7	5,386,341	01/1995	Olson et al.		
A8	5,397,921	03/1995	Karnezos		
A9	5,404,044	04/1995	Booth et al.		
A10	5,409,865	04/1995	Karnezos		
A11	5,422,205	06/1995	Inoue et al.		
A12	5,438,477	08/1995	Pasch		
A13	5,448,511	09/1995	Paurus et al.		
A14	5,468,681	11/1995	Pasch		
A15	5,489,804	02/1996	Pasch		
A16	5,504,277	04/1996	Danner		
A17	5,598,033	01/1997	Behlen et al.		
A18	5,646,446	07/1997	Nicewarner, Jr. et al.		
A19	5,663,530	09/1997	Schueller et al.		
A20	5,668,405	09/1997	Yamashita		
A21	5,674,785	10/1997	Akram et al.		
A22	5,697,148	12/1997	Lance, Jr. et al.		
A23	5,719,449	02/1998	Strauss		
A24	5,721,151	02/1998	Padmanabhan et al.		
A25	5,739,585	04/1998	Akram et al.		
A26	5,742,100	04/1998	Schroeder et al.		
A27	5,747,982	05/1998	Dromgoole et al.		
A28	5,752,182	05/1998	Nakatsuka et al.		
A29	5,758,413	06/1998	Chong et al.		
A30	5,798,285	08/1998	Bentlage et al.		
A31	5,798,567	08/1998	Kelly et al.		
A32	5,805,422	09/1998	Otake et al.		
A33	5,818,113	10/1998	Iseki et al.		
A34	5,821,624	10/1998	Pasch		

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

Patent

Attorney Docket No. MTI-31607

<p>U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p>	ATTY. DOCKET NO. MTI-31607 Applicant Teck Kheng Lee Filing Date January 16, 2002	Serial No. 10/050,507 Confirmation No. 7687 Group Art Unit 2813
---	--	---

Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub- Class
A35	5,834,338	11/1998	Takeda et al.		
A36	5,834,366	11/1998	Akram		
A37	5,834,848	11/1998	Iwasaki		
A38	5,835,355	11/1998	Dordi		
A39	5,843,808	12/1998	Karnezos		
A40	5,844,168	12/1998	Schueller et al.		
A41	5,866,953	02/1999	Akram et al.		
A42	5,886,408	03/1999	Ohki et al.		
A43	5,891,753	04/1999	Akram		
A44	5,898,224	04/1999	Akram		
A45	5,973,389	10/1999	Culnane et al.		
A46	5,973,404	10/1999	Akram et al.		
A47	5,977,640	11/1999	Bertin et al.		
A48	5,982,030	11/1999	MacIntrye		
A49	5,984,691	11/1999	Brodsky et al.		
A50	5,990,545	11/1999	Schueller et al.		
A51	5,991,161	11/1999	Samaras et al.		
A52	6,005,776	12/1999	Holman et al.		
A53	6,008,543	12/1999	Iwabuchi		
A54	6,011,694	01/2000	Hirakawa		
A55	6,013,948	01/2000	Akram et al.		
A56	6,020,629	02/2000	Farnworth et al.		
A57	6,022,761	02/2000	Grupen-Shemansky et al.		
A58	6,024,584	02/2000	Lemke et al.		
A59	6,027,346	02/2000	Sinsheimer et al.		
A60	6,028,365	02/2000	Akram et al.		
A61	6,034,427	03/2000	Lan et al.		
A62	6,039,889	03/2000	Zhang et al.		
A63	6,040,630	03/2000	Panchou et al.		
A64	6,050,832	04/2000	Lee et al.		
A65	6,057,178	05/2000	Galuschki et al.		
A66	6,060,782	05/2000	Ohsono et al.		
A67	6,064,114	05/2000	Higgins, III		
A68	6,072,233	06/2000	Corisis et al.		
A69	6,074,897	06/2000	Degani et al.		
A70	6,075,710	06/2000	Lau		

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313	ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant Teck Kheng Lee	Confirmation No. 7687
	Filing Date January 16, 2002	Group Art Unit 2813

Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub-Class
A71	6,079,991	06/2000	Lemke et al.		
A72	6,093,035	07/2000	Lemke et al.		
A73	6,116,921	09/2000	Scholz et al.		
A74	6,124,631	09/2000	Cardot et al.		
A75	6,127,736	10/2000	Akram		
A76	6,133,637	10/2000	Hikita et al.		
A77	6,137,062	10/2000	Zimmerman		
A78	6,137,164	10/2000	Yew et al.		
A79	6,137,183	10/2000	Sako		
A80	6,157,541	12/2000	Hacke		
A81	6,165,885	12/2000	Gaynes et al.		
A82	6,172,422 B1	01/2001	Chigawa et al.		
A83	6,179,598 B1	01/2001	Brand		
A84	6,191,487 B1	02/2001	Rodenbeck et al.		
A85	6,208,521 B1	03/2001	Nakatsuka		
A86	6,212,768 B1	04/2001	Murakami		
A87	6,214,156 B1	04/2001	Takano et al.		
A88	6,218,202 B1	04/2001	Yew et al.		
A89	6,219,911 B1	04/2001	Estes et al.		
A90	6,221,763 B1	04/2001	Gilton et al.		
A91	6,225,688 B1	05/2001	Kim et al.		
A92	6,229,711 B1	05/2001	Yoneda		
A93	6,262,895 B1	07/2001	Forthun		
A94	6,291,775 B1	09/2001	Saitoh		
A95	6,294,455 B1	09/2001	Ahn		
A96	6,300,679 B1	10/2001	Mukerji et al.		
A97	6,310,288 B1	10/2001	Moden		
A98	6,323,060 B1	11/2001	Isaak		
A99	6,338,985	01/2002	Greenwood		
A100	6,429,516 B1	08/2002	Tsunoi		
A101	6,432,737 B1	08/2002	Webster		
A102	6,468,831	10/2002	Leong et al.		
A103	6,482,676	11/2002	Tsumoi et al.		
A104	6,489,676	12/2002	Taniguchi et al.		
A105	6,489,687 B1	12/2002	Hashimoto		
A106	6,492,737 B1	12/2002	Imasu et al.		

Examiner Initials

Date Considered

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313		ATTY. DOCKET NO. MTI-31607	Serial No. 10/050,507
		Applicant Teck Kheng Lee	Confirmation No. 7687
		Filing Date January 16, 2002	Group Art Unit 2813

Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub-Class
A107	6,515,324 B2	02/2003	Shibuya et al.		
A108	6,518,677 B1	02/2003	Capote et al.		
A109	6,586,830 B2	07/2003	Saito		
A110	6,714,418	03/2004	Frankowsky et al.		
A111	6,744,122	06/2004	Hashimoto		
A112	6,756,251	06/2004	Lee		
A113	2002/0045611 A1	04/2002	Abrams et al.		
A114	2002/0079594 A1	06/2002	Sakurai		
A115	2002/0167092 A1	11/2002	Fee et al.		
A116	2002/0185661 A1	12/2002	Kawanobe et al.		

Examiner Initials	Date Considered
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

**This Page is Inserted by IFW Indexing and Scanning
Operations and is not part of the Official Record**

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- BLACK BORDERS**
- IMAGE CUT OFF AT TOP, BOTTOM OR SIDES**
- FADED TEXT OR DRAWING**
- BLURRED OR ILLEGIBLE TEXT OR DRAWING**
- SKEWED/SLANTED IMAGES**
- COLOR OR BLACK AND WHITE PHOTOGRAPHS**
- GRAY SCALE DOCUMENTS**
- LINES OR MARKS ON ORIGINAL DOCUMENT**
- REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY**
- OTHER:** _____

IMAGES ARE BEST AVAILABLE COPY.

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.